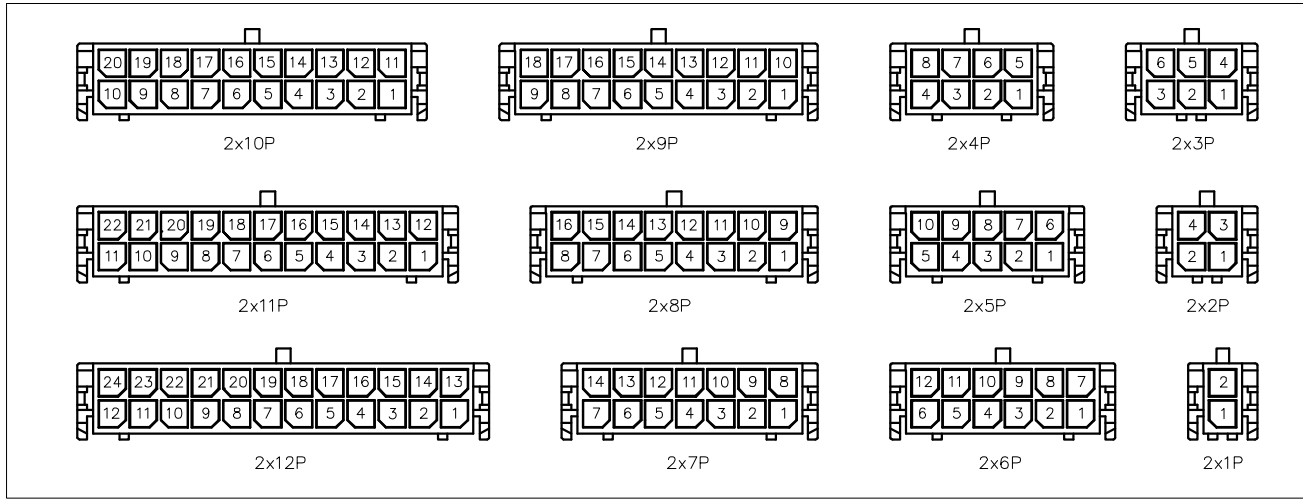


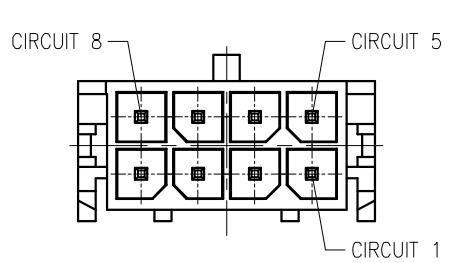
	1	2	3
Poles	DIM.A	DIM.B	
2x1P	-	6.65	
2x2P	3.00	9.65	
2x3P	6.00	12.65	
2x4P	9.00	15.65	
2x5P	12.00	18.65	
2x6P	15.00	21.65	
2x7P	18.00	24.65	
2x8P	21.00	27.65	
2x9P	24.00	30.65	
2x10P	27.00	33.65	
2x11P	30.00	36.65	
2x12P	33.00	39.65	

CIRCUIT SIZE LAYOUT

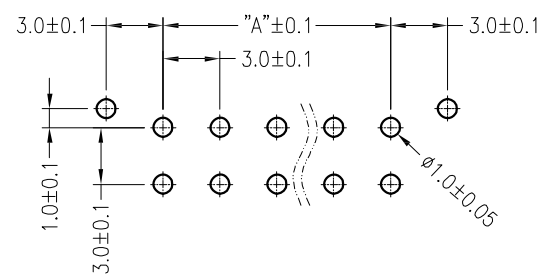


SPECIFICATION:

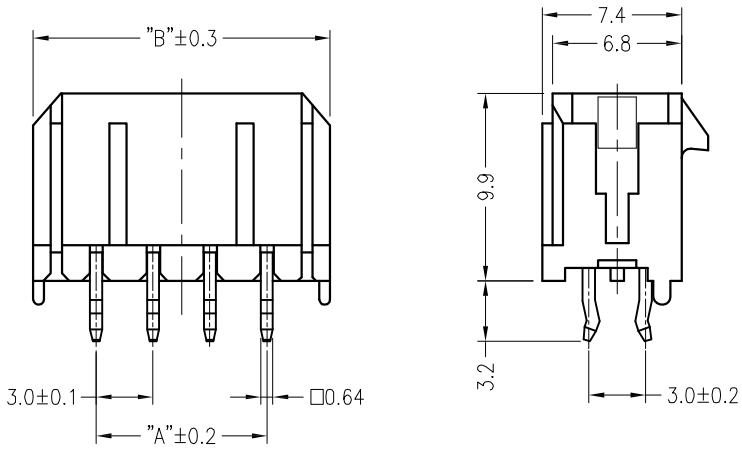
- Voltage rating:
AC, DC, 250V(rms)
- Current rating:
5A AWG #20
- Withstand voltage:
1000V AC/minute
- Working Temperature:
-25°C~ +85°C
- Insulation resistance:
≥ 1000M Ω
- Contact resistance:
≤ 10m Ω
- Terminal mtr'l:
BRASS
- Material:
Housing-PA9T,UL94V-0
- Applicable Wire:
AWG #24~ AWG #20



RoHS
Compliant



RECOMMENDED PCB LAYOUT



Ordering Information

WJ - **2** - **XX** - **PT** - **3001-4-44**
 3.0P Wafer Solder/PCB Total PIN Contact Plated Packing
 1:DIP RA 2:DIP VT 3:SMT RA PT: Tin 4:Tube
 4:SMT VT

REV.	REVISION RECORD	DATE	General Tolerances		
A	Original	08/27/13'	LINEAR	0.0 ±0.35 0.00±0.20	ANGLES ±3°
B	Revised	06/02/16'	UNIT: mm		
C	Revised	02/13/17'	A4	NAME	DATE
			APPROVED	WENDY	
			DESIGNER	WHITE	
			DRAWN	ANGEL	
			TITLE: 3.0P Wafer Dual Rows DIP Vertical Kick Type		
			DWG.NO.: WJ2XXPT30014-44		REV. C
			SCALE	1 : 1	SHEET 1 OF 1